



MICRO POWDERS

5N PLUS

ULTRAFINE POWDERS ENABLING TECHNOLOGIES



Wide range of melting alloys



Tightly controlled size distribution

5N PLUS MICRO POWDERS HAS DEVELOPED A PROPRIETARY ATOMIZING TECHNOLOGY PARTICULARLY EFFECTIVE IN PRODUCING ULTRAFINE SOLDER POWDERS RANGING FROM 1 TO 25 μ M.

FEATURES

- Low oxygen content
- Spherical particles
- Size from Type 5 to Type 10

APPLICATIONS

- Screen Printing
- Dispensing and Jet Printing
- MiniLED and MicroLED packaging

5N Plus Technology

Type 5	Type 6	Type 7	Type 8	Type 9	Type 10
[15 – 25 μ m]	[5 – 15 μ m]	[2 – 11 μ m]	[1 – 8 μ m]	[1 – 5 μ m]	[1 – 3 μ m]



Solder Powders

Composition, wt.%	Solidifying range (°C)
Sn42Bi58	138*
Sn42Bi57Ag1	139*
Sn96.5-Ag3.0-Cu0.5	217-220
Sn95.5-Ag4.0-Cu0.5	217-220
Sn99.3-Cu0.7	227*
Sn95-Ag5	221-245
Sn	232
Sn95-Sb5	237-240
Sn90-Sb10	243-257
Bi97.5Ag2.5	262-267
Bi	271

Low Melting Point Alloys

Composition, wt.%	Solidifying range (°C)
Bi32.5-Sn16.5-In51	61*
Bi33.7-In66.3	72*
Bi57-Sn17-In26	78*
Bi67-In33	109*
Sn50-In50	118-120
Bi58-Sn42	138*
Bi57-Sn42-Ag1	139*
In97-Ag3	145*
Bi50-Sn50	138-154
Bi40-Sn60	138-170
In	157
Sn91-Zn9	199*

* Eutectic or near-eutectic alloys

High Temperature Powders

Composition, wt.%	Solidifying range (°C)
Sn80-Cu20	227-520
Cu65-Sn35	725-750
Ag72-Cu28	779*
Cu90-Sn10	860-1010
Cu	1085

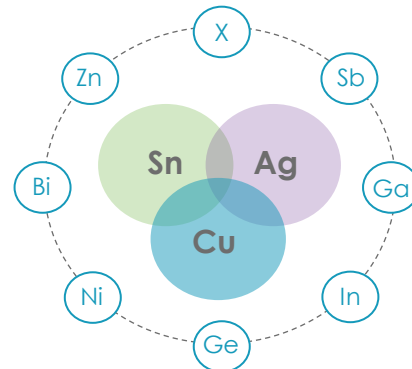
Low Alpha Powders

Low alpha count powders are now an integral part of our product line-up for the electronic market. Sizes available include Type 5 to Type 8 in a variety of Pb-free alloys.

ULA <0.002 c/h/cm²

SULA <0.001 c/h/cm²

Customized Metal Powders



We work closely with our customers to enhance the performance of their products. This often involves customized alloy compositions and particle size distributions for improvements in

✓ Reliability ✓ Printability ✓ Solderability